



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  *: Required Field

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2013-06-05
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Antonella Lanzafame	<b>Representative Title</b>	AMS/IPD Materials Declaration Champion)
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**


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Legal Statement		
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>
		Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	TLD2*EZ626W2	A	SH1A	2013-06-05
Amount	UoM	Unit type	ST ECOPACK Grade	
1380.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.20,9.15,4.5	2	gull wing	
Comment	D2 D2PAK			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList :REACH-19 Dec 2012				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	TLD2*E2626W2					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	5.699	mg	supplier	die	Silicon (Si)	7440-21-3		5.505	mg	965959	3989
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.078	mg	13687	57
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.026	mg	4562	19
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.041	mg	7194	30
die (s)				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.003	mg	526	2
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.008	mg	1404	6
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.038	mg	6668	28
Leadframe	Copper & its alloys	779.754	mg	supplier	alloy	Copper (Cu)	7440-50-8		775.923	mg	995087	562263
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.357	mg	458	259
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.653	mg	837	473
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		2.804	mg	3596	2032
Leadframe				supplier	metallization	Phosphorus (P)	12185-10-3		0.017	mg	22	12
Soft solder	Solder	4.398	mg	JIG R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	4.2	mg	954980	3043
Soft solder				supplier	solder	Silver (Ag)	7440-22-4		0.11	mg	25011	80
Soft solder				supplier	solder	Tin (Sn)	7440-31-5		0.088	mg	20009	64
Bonding wire	Other inorganic materials	0.375	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.374	mg	997333	271
Bonding wire				supplier	wire	Magnesium (Mg)	7439-95-4		0.001	mg	2667	1
encapsulation	Other Organic Materials	587.285	mg	supplier	mold compound	Epoxy Resin	Proprietary		17.619	mg	30001	12767
encapsulation				supplier	mold compound	2,2'-(1,3,3',5,5'-tetramethyl-1,1'-biphenyl)-4,4'	EC 413-900-7		23.492	mg	40001	17023
encapsulation				supplier	mold compound	phenol resin	Proprietary		29.365	mg	50001	21279
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		513.873	mg	874998	372372
encapsulation				supplier	mold compound	Carbon black	1333-86-4		2.936	mg	4999	2128
connections coating	Solder	2.489	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		2.489	mg	1000000	1804